

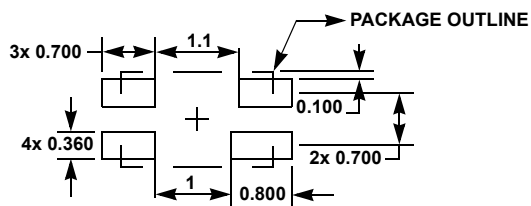
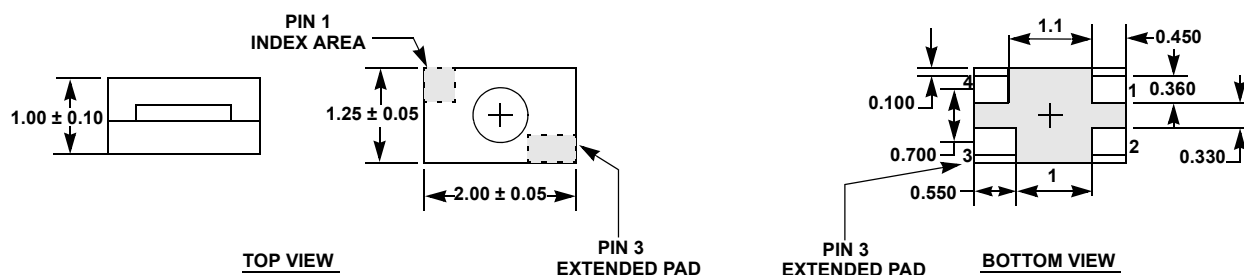
Plastic Packages for Integrated Circuits

Package Outline Drawing

L4.2.00x1.25

4 LD OPTICAL CHIP ON BOARD PACKAGE (COB)

Rev 3, 2/14



TYPICAL RECOMMENDED LAND PATTERN

NOTES:

1. Dimensions are in millimeters.
Dimensions in () for Reference Only.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Pin 1 is diagonal to extended Pad Pin 3 on bottom surface.